



## Material Content Data Sheet



<b>Sales Product Name</b>				BSZ120P03NS3 G		<b>Issued</b>		29. August 2013	
<b>MA#</b>				MA000734126					
<b>Package</b>				PG-TSDSON-8-2		<b>Weight*</b>		38.42 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.346	3.50	3.50	35023	35023	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		55		
	non noble metal	zinc	7440-66-6	0.008	0.02		218		
	non noble metal	iron	7439-89-6	0.168	0.44		4364		
wire	non noble metal	copper	7440-50-8	6.808	17.72	18.19	177191	181828	
	non noble metal	copper	7440-50-8	0.053	0.14	0.14	1381	1381	
	encapsulation	organic material	carbon black	1333-86-4	0.035	0.09		901	
	plastics	epoxy resin	-	1.783	4.64		46412		
	inorganic material	silicondioxide	60676-86-0	15.494	40.33	45.06	403289	450602	
leadfinish	non noble metal	tin	7440-31-5	0.387	1.01	1.01	10077	10077	
plating	noble metal	silver	7440-22-4	0.963	2.51	2.51	25054	25054	
solder	noble metal	silver	7440-22-4	0.037	0.10		972		
	non noble metal	tin	7440-31-5	0.030	0.08		777		
	non noble metal	lead	7439-92-1	1.426	3.71	3.89	37121	38870	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		28		
	non noble metal	zinc	7440-66-6	0.004	0.01		112		
	non noble metal	iron	7439-89-6	0.086	0.22		2244		
heat sink CLIP	non noble metal	copper	7440-50-8	3.501	9.11	9.34	91129	93513	
	inorganic material	phosphorus	7723-14-0	0.002	0.00		49		
	non noble metal	zinc	7440-66-6	0.008	0.02		196		
	non noble metal	iron	7439-89-6	0.151	0.39		3928		
	non noble metal	copper	7440-50-8	6.127	15.95	16.36	159479	163652	
*deviation	< 10%			Sum in total:		100,00		1000000	

### Important Remarks:

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